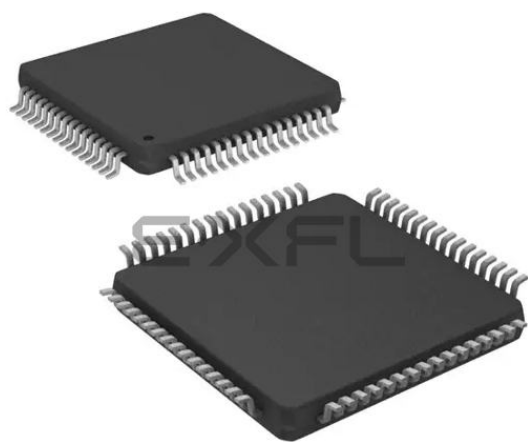




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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I ² C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	53
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx440f512ht-80v-pt

FIGURE 4-6: MEMORY MAP ON RESET FOR PIC32MX340F512H, PIC32MX360F512L, PIC32MX440F512H AND PIC32MX460F512L DEVICES⁽¹⁾

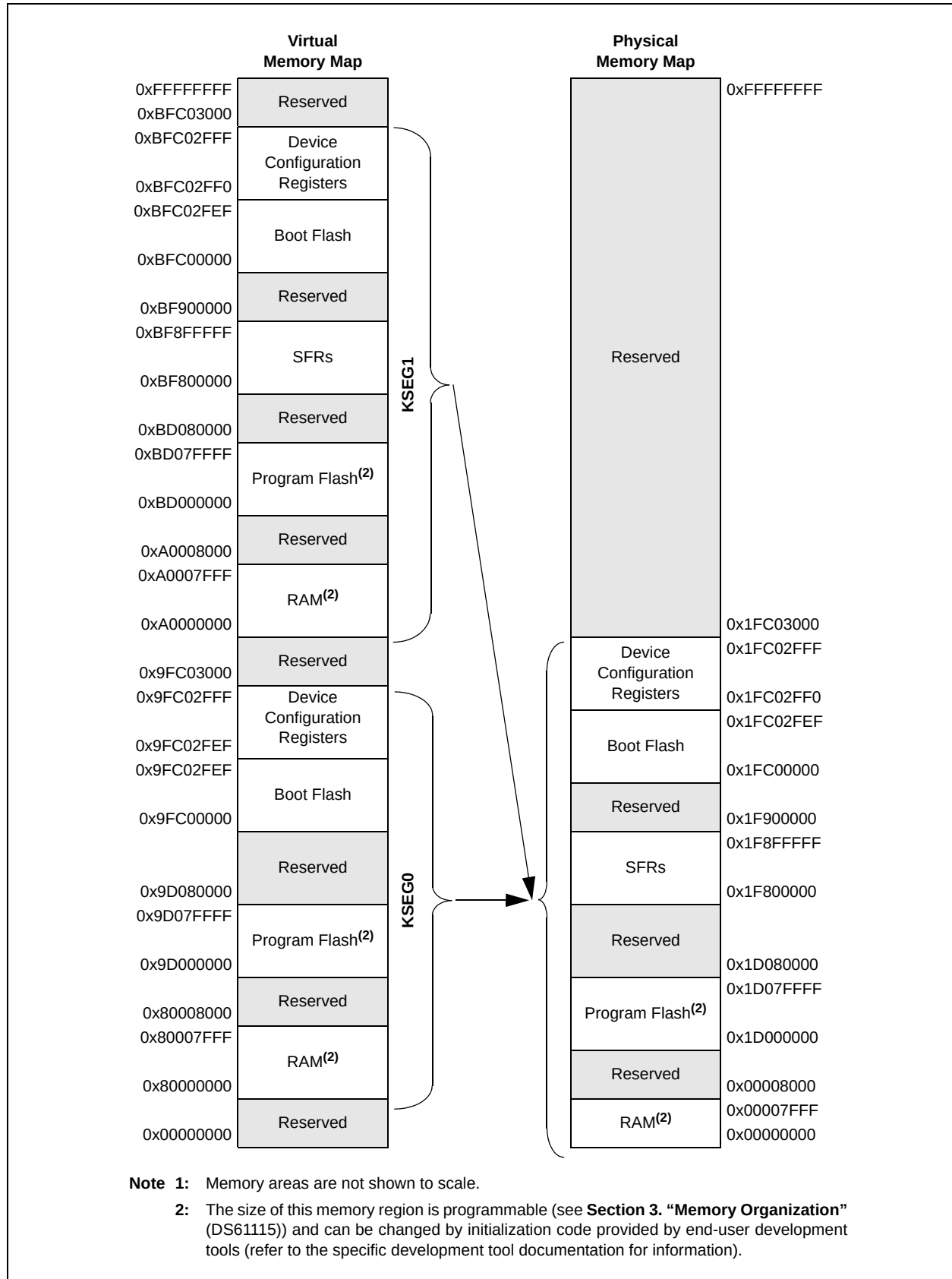


TABLE 4-5: INTERRUPT REGISTERS MAP FOR PIC32MX440F128H, PIC32MX440F256H AND PIC32MX440F512H DEVICES ONLY⁽¹⁾

Virtual Address (BF88..#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
1000	INTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SS0	0000
		15:0	—	—	—	MVEC	—	TPC<2:0>			—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP	0000
1010	INTSTAT ⁽²⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	SRIPL<2:0>			—	—	VEC<5:0>					—	—
1020	IPTMR	31:16	IPTMR<31:0>																0000
		15:0																	0000
1030	IFS0	31:16	I2C1MIF	I2C1SIF	I2C1BIF	U1TXIF	U1RXIF	U1EIF	—	—	—	OC5IF	IC5IF	T5IF	INT4IF	OC4IF	IC4IF	T4IF	0000
		15:0	INT3IF	OC3IF	IC3IF	T3IF	INT2IF	OC2IF	IC2IF	T2IF	INT1IF	OC1IF	IC1IF	T1IF	INT0IF	CS1IF	CS0IF	CTIF	0000
1040	IFS1	31:16	—	—	—	—	—	—	USBIF	FCEIF	—	—	—	—	DMA3IF	DMA2IF	DMA1IF	DMA0IF	0000
		15:0	RTCCIF	FSCMIF	I2C2MIF	I2C2SIF	I2C2BIF	U2TXIF	U2RXIF	U2EIF	SPI2RXIF	SPI2TXIF	SPI2EIF	CMP2IF	CMP1IF	PMPIF	AD1IF	CNIF	0000
1060	IEC0	31:16	I2C1MIE	I2C1SIE	I2C1BIE	U1TXIE	U1RXIE	U1EIE	—	—	—	OC5IE	IC5IE	T5IE	INT4IE	OC4IE	IC4IE	T4IE	0000
		15:0	INT3IE	OC3IE	IC3IE	T3IE	INT2IE	OC2IE	IC2IE	T2IE	INT1IE	OC1IE	IC1IE	T1IE	INT0IE	CS1IE	CS0IE	CTIE	0000
1070	IEC1	31:16	—	—	—	—	—	—	USBIE	FCEIE	—	—	—	—	DMA3IE	DMA2IE	DMA1IE	DMA0IE	0000
		15:0	RTCCIE	FSCMIE	I2C2MIE	I2C2SIE	I2C2BIE	U2TXIE	U2RXIE	U2EIE	SPI2RXIE	SPI2TXIE	SPI2EIE	CMP2IE	CMP1IE	PMPIE	AD1IE	CNIE	0000
1090	IPC0	31:16	—	—	—	INT0IP<2:0>			INT0IS<1:0>			—	—	—	CS1IP<2:0>			CS1IS<1:0>	0000
		15:0	—	—	—	CS0IP<2:0>			CS0IS<1:0>			—	—	—	CTIP<2:0>			CTIS<1:0>	0000
10A0	IPC1	31:16	—	—	—	INT1IP<2:0>			INT1IS<1:0>			—	—	—	OC1IP<2:0>			OC1IS<1:0>	0000
		15:0	—	—	—	IC1IP<2:0>			IC1IS<1:0>			—	—	—	T1IP<2:0>			T1IS<1:0>	0000
10B0	IPC2	31:16	—	—	—	INT2IP<2:0>			INT2IS<1:0>			—	—	—	OC2IP<2:0>			OC2IS<1:0>	0000
		15:0	—	—	—	IC2IP<2:0>			IC2IS<1:0>			—	—	—	T2IP<2:0>			T2IS<1:0>	0000
10C0	IPC3	31:16	—	—	—	INT3IP<2:0>			INT3IS<1:0>			—	—	—	OC3IP<2:0>			OC3IS<1:0>	0000
		15:0	—	—	—	IC3IP<2:0>			IC3IS<1:0>			—	—	—	T3IP<2:0>			T3IS<1:0>	0000
10D0	IPC4	31:16	—	—	—	INT4IP<2:0>			INT4IS<1:0>			—	—	—	OC4IP<2:0>			OC4IS<1:0>	0000
		15:0	—	—	—	IC4IP<2:0>			IC4IS<1:0>			—	—	—	T4IP<2:0>			T4IS<1:0>	0000
10E0	IPC5	31:16	—	—	—	—	—	—	—	—	—	—	—	—	OC5IP<2:0>			OC5IS<1:0>	0000
		15:0	—	—	—	IC5IP<2:0>			IC5IS<1:0>			—	—	—	T5IP<2:0>			T5IS<1:0>	0000
10F0	IPC6	31:16	—	—	—	AD1IP<2:0>			AD1IS<1:0>			—	—	—	CNIP<2:0>			CNIS<1:0>	0000
		15:0	—	—	—	I2C1IP<2:0>			I2C1IS<1:0>			—	—	—	U1IP<2:0>			U1IS<1:0>	0000
1100	IPC7	31:16	—	—	—	SPI2IP<2:0>			SPI2IS<1:0>			—	—	—	CMP2IP<2:0>			CMP2IS<1:0>	0000
		15:0	—	—	—	CMP1IP<2:0>			CMP1IS<1:0>			—	—	—	PMP1P<2:0>			PMP1S<1:0>	0000
1110	IPC8	31:16	—	—	—	RTCCIP<2:0>			RTCCIS<1:0>			—	—	—	FSCMIP<2:0>			FSCMIS<1:0>	0000
		15:0	—	—	—	I2C2IP<2:0>			I2C2IS<1:0>			—	—	—	U2IP<2:0>			U2IS<1:0>	0000
1120	IPC9	31:16	—	—	—	DMA3IP<2:0>			DMA3IS<1:0>			—	—	—	DMA2IP<2:0>			DMA2IS<1:0>	0000
		15:0	—	—	—	DMA1IP<2:0>			DMA1IS<1:0>			—	—	—	DMA0IP<2:0>			DMA0IS<1:0>	0000
1140	IPC11	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	USBIP<2:0>			USBIS<1:0>			—	—	—	FCEIP<2:0>			FCEIS<1:0>	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Except where noted, all registers in this table have corresponding CLR, SET, and INV registers at their virtual addresses, plus offsets of 0x4, 0x8, and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

2: This register does not have associated CLR, SET, and INV registers.

TABLE 4-14: DMA GLOBAL REGISTERS MAP FOR PIC32MX340FXXXX/360FXXXX/440FXXXX/460XXXX DEVICES ONLY

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3000	DMACON ⁽¹⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	SUSPEND	—	—	—	—	—	—	—	—	—	—	—	—	0000
3010	DMASTAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RDWR	—	DMACH<1:0>	—	0000
3020	DMAADDR	31:16	DMAADDR<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

TABLE 4-15: DMA CRC REGISTERS MAP FOR PIC32MX340FXXXX/360FXXXX/440FXXXX/460XXXX DEVICES ONLY⁽¹⁾

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3030	DCRCCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	PLEN<3:0>				CRCEN	CRCAPP	—	—	—	—	CRCCH<1:0>		0000
3040	DCRCDATA	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	DCRCDATA<15:0>																0000
3050	DCRCXOR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	DCRCXOR<15:0>																0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

TABLE 4-16: DMA CHANNELS 0-3 REGISTERS MAP FOR PIC32MX340FXXXX/360FXXXX/440FXXXX/460XXXX DEVICES ONLY⁽¹⁾ (CONTINUED)

Virtual Address (BF88_#)	Register Name	Bit Range	Bits															All Resets	
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1		16/0
3260	DCH2DPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	—	—	—	—	—	—	—	CHDPTR<7:0>								0000	
3270	DCH2CSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	—	—	—	—	—	—	—	CHCSIZ<7:0>								0000	
3280	DCH2CPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	—	—	—	—	—	—	—	CHCPTR<7:0>								0000	
3290	DCH2DAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	—	—	—	—	—	—	—	CHPDAT<7:0>								0000	
32A0	DCH3CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	—	—	—	—	—	—	—	CHCHNS	CHEN	CHAED	CHCHN	CHAEN	—	CHEDET	CHPRI<1:0>	0000	
32B0	DCH3ECON	31:16	—	—	—	—	—	—	—	CHAIRQ<7:0>								00FF	
		15:0	CHSIRQ<7:0>								CFORCE	CABORT	PATEN	SIRQEN	AIRQEN	—	—	—	FF00
32C0	DCH3INT	31:16	—	—	—	—	—	—	—	—	CHSDIE	CHSHIE	CHDDIE	CHDHIE	CHBCIE	CHCCIE	CHTAIE	CHERIE	0000
		15:0	—	—	—	—	—	—	—	—	CHSDIF	CHSHIF	CHDDIF	CHDHIF	CHBCIF	CHCCIF	CHTAIF	CHERIF	0000
32D0	DCH3SSA	31:16	CHSSA<31:0>															0000	
		15:0																0000	
32E0	DCH3DSA	31:16	CHDSA<31:0>															0000	
		15:0																0000	
32F0	DCH3SSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	—	—	—	—	—	—	—	CHSSIZ<7:0>								0000	
3300	DCH3DSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	—	—	—	—	—	—	—	CHDSIZ<7:0>								0000	
3310	DCH3SPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	—	—	—	—	—	—	—	CHSTR<7:0>								0000	
3320	DCH3DPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	—	—	—	—	—	—	—	CHDPTR<7:0>								0000	
3330	DCH3CSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	—	—	—	—	—	—	—	CHCSIZ<7:0>								0000	
3340	DCH3CPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	—	—	—	—	—	—	—	CHCPTR<7:0>								0000	
3350	DCH3DAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	—	—	—	—	—	—	—	CHPDAT<7:0>								0000	

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers except DCHxSPTR, DCHxDPTR and DCHxCPTR have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

TABLE 4-25: PORTD REGISTERS MAP FOR PIC32MX320F128L, PIC32MX340F128L, PIC32MX360F256L, PIC32MX360F512L, PIC32MX440F128L, PIC32MX460F256L AND PIC32MX460F512L DEVICES ONLY⁽¹⁾

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
60C0	TRISD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	TRISD15	TRISD14	TRISD13	TRISD12	TRISD11	TRISD10	TRISD9	TRISD8	TRISD7	TRISD6	TRISD5	TRISD4	TRISD3	TRISD2	TRISD1	TRISD0	FFFF
60D0	PORTD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	RD15	RD14	RD13	RD12	RD11	RD10	RD9	RD8	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	xxxx
60E0	LATD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	LATD15	LATD14	LATD13	LATD12	LATD11	LATD10	LATD9	LATD8	LATD7	LATD6	LATD5	LATD4	LATD3	LATD2	LATD1	LATD0	xxxx
60F0	ODCD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ODCD15	ODCD14	ODCD13	ODCD12	ODCD11	ODCD10	ODCD9	ODCD8	ODCD7	ODCD6	ODCD5	ODCD4	ODCD3	ODCD2	ODCD1	ODCD0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

TABLE 4-26: PORTD REGISTERS MAP FOR PIC32MX320F032H, PIC32MX320F064H, PIC32MX320F128H, PIC32MX340F128H, PIC32MX340F256H, PIC32MX340F512H, PIC32MX420F032H, PIC32MX440F128H, PIC32MX440F256H AND PIC32MX440F512H DEVICES ONLY⁽¹⁾

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
60C0	TRISD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	TRISD11	TRISD10	TRISD9	TRISD8	TRISD7	TRISD6	TRISD5	TRISD4	TRISD3	TRISD2	TRISD1	TRISD0	0FFF
60D0	PORTD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	RD11	RD10	RD9	RD8	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	xxxx
60E0	LATD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	LATD11	LATD10	LATD9	LATD8	LATD7	LATD6	LATD5	LATD4	LATD3	LATD2	LATD1	LATD0	xxxx
60F0	ODCD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	ODCD11	ODCD10	ODCD9	ODCD8	ODCD7	ODCD6	ODCD5	ODCD4	ODCD3	ODCD2	ODCD1	ODCD0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

TABLE 4-27: PORTE REGISTERS MAP FOR PIC32MX320F128L, PIC32MX340F128L, PIC32MX360F256L, PIC32MX360F512L, PIC32MX440F128L, PIC32MX460F256L AND PIC32MX460F512L DEVICES ONLY⁽¹⁾

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
6100	TRISE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	TRISE9	TRISE8	TRISE7	TRISE6	TRISE5	TRISE4	TRISE3	TRISE2	TRISE1	TRISE0	03FF
6110	PORTE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	RE9	RE8	RE7	RE6	RE5	RE4	RE3	RE2	RE1	RE0	xxxx
6120	LATE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	LATE9	LATE8	LATE7	LATE6	LATE5	LATE4	LATE3	LATE2	LATE1	LATE0	xxxx
6130	ODCE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	ODCE9	ODCE8	ODCE7	ODCE6	ODCE5	ODCE4	ODCE3	ODCE2	ODCE1	ODCE0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

TABLE 4-28: PORTE REGISTERS MAP FOR PIC32MX320F032H, PIC32MX320F064H, PIC32MX320F128H, PIC32MX340F128H, PIC32MX340F256H, PIC32MX340F512H, PIC32MX420F032H, PIC32MX440F128H, PIC32MX440F256H AND PIC32MX440F512H DEVICES ONLY⁽¹⁾

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
6100	TRISE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	TRISE7	TRISE6	TRISE5	TRISE4	TRISE3	TRISE2	TRISE1	TRISE0	00FF
6110	PORTE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	RE7	RE6	RE5	RE4	RE3	RE2	RE1	RE0	xxxx
6120	LATE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	LATE7	LATE6	LATE5	LATE4	LATE3	LATE2	LATE1	LATE0	xxxx
6130	ODCE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	ODCE7	ODCE6	ODCE5	ODCE4	ODCE3	ODCE2	ODCE1	ODCE0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

5.0 FLASH PROGRAM MEMORY

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 5. “Flash Program Memory”** (DS61121) of the “*PIC32 Family Reference Manual*”, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

RTSP is performed by software executing from either Flash or RAM memory. EJTAG is performed using the EJTAG port of the device and a EJTAG capable programmer. ICSP is performed using a serial data connection to the device and allows much faster programming times than RTSP. RTSP techniques are described in this chapter. The ICSP and EJTAG methods are described in the “*PIC32MX Flash Programming Specification*” (DS61145), which can be downloaded from the Microchip web site.

Note: Flash LVD Delay (LVDstartup) must be taken into account between setting up and executing any Flash command operation. See Example 5-1 for a code example to set up and execute a Flash command operation.

PIC32MX3XX/4XX devices contain an internal program Flash memory for executing user code. There are three methods by which the user can program this memory:

- Run-Time Self Programming (RTSP)
- In-Circuit Serial Programming™ (ICSP™)
- EJTAG Programming

EXAMPLE 5-1:

```
NVMCON = 0x4004;           // Enable and configure for erase operation
Wait(delay);               // Delay for 6 μs for LVDstartup

NVMKEY = 0xAA996655;
NVMKEY = 0x556699AA;
NVMCONSET = 0x8000;         // Initiate operation

while(NVMCONbits.WR==1);   // Wait for current operation to complete
```


PIC32MX3XX/4XX

NOTES:

PIC32MX3XX/4XX

NOTES:

21.0 REAL-TIME CLOCK AND CALENDAR (RTCC)

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 29. “Real-Time Clock and Calendar (RTCC)”** (DS61125) of the “PIC32 Family Reference Manual”, which is available from the Microchip web site (www.microchip.com/PIC32).

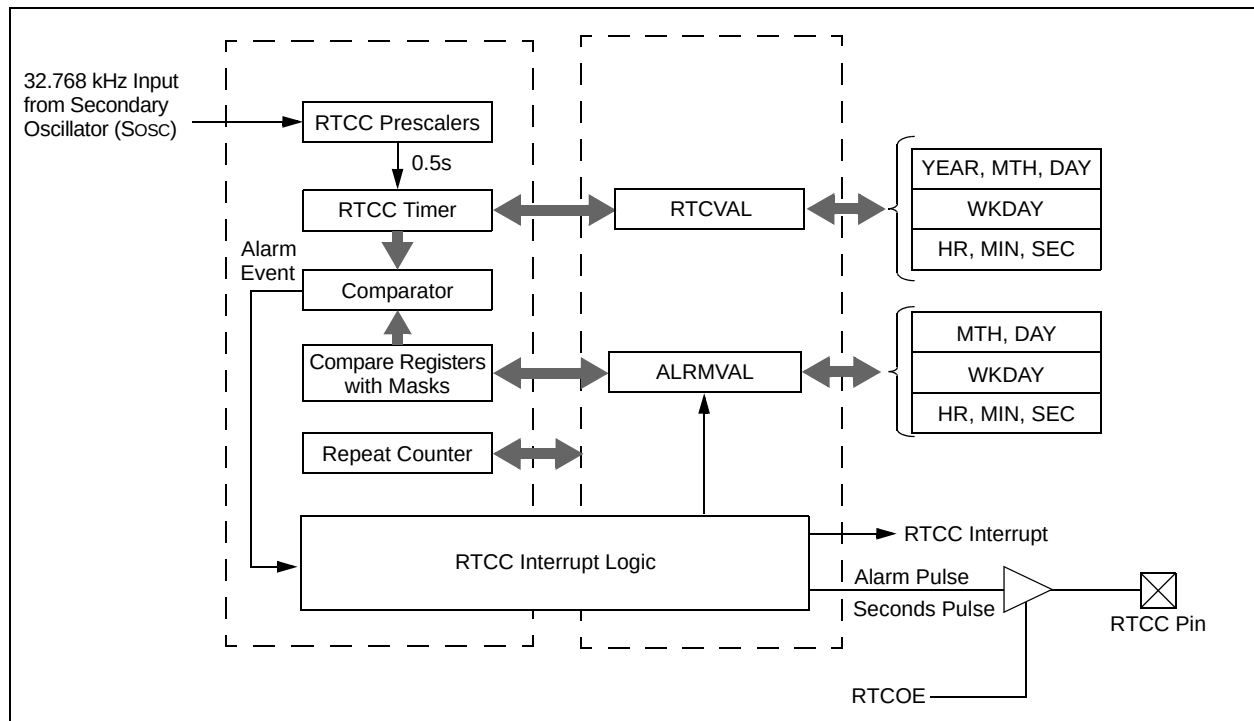
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The PIC32MX RTCC module is intended for applications in which accurate time must be maintained for extended periods of time with minimal or no CPU intervention. Low-power optimization provides extended battery lifetime while keeping track of time.

The following are some of the key features of this module:

- Time: Hours, Minutes and Seconds
- 24-Hour Format (Military Time)
- Visibility of One-Half-Second Period
- Provides Calendar: Weekday, Date, Month and Year
- Alarm Intervals are configurable for Half of a Second, One Second, 10 Seconds, One Minute, 10 Minutes, One Hour, One Day, One Week, One Month and One Year
- Alarm Repeat with Decrementing Counter
- Alarm with Indefinite Repeat: Chime
- Year Range: 2000 to 2099
- Leap Year Correction
- BCD Format for Smaller Firmware Overhead
- Optimized for Long-Term Battery Operation
- Fractional Second Synchronization
- User Calibration of the Clock Crystal Frequency with Auto-Adjust
- Calibration Range: ± 0.66 Seconds Error per Month
- Calibrates up to 260 ppm of Crystal Error
- Requirements: External 32.768 kHz Clock Crystal
- Alarm Pulse or Seconds Clock Output on RTCC pin

FIGURE 21-1: RTCC BLOCK DIAGRAM



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NOTES:

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REGISTER 26-1: DEVCFG0: DEVICE CONFIGURATION WORD 0 (CONTINUED)

bit 19-12 **PWP<7:0>**: Program Flash Write-Protect bits

Prevents selected program Flash memory pages from being modified during code execution. The PWP bits represent the one's complement of the number of write protected program Flash memory pages.

11111111 = Disabled
11111110 = 0xBD00_0FFF
11111101 = 0xBD00_1FFF
11111100 = 0xBD00_2FFF
11111011 = 0xBD00_3FFF
11111010 = 0xBD00_4FFF
11111001 = 0xBD00_5FFF
11111000 = 0xBD00_6FFF
11110111 = 0xBD00_7FFF
11110110 = 0xBD00_8FFF
11110101 = 0xBD00_9FFF
11110100 = 0xBD00_AFFF
11110011 = 0xBD00_BFFF
11110010 = 0xBD00_CFFF
11110001 = 0xBD00_DFFF
11110000 = 0xBD00_EFFF
11101111 = 0xBD00_FFFF
.
.
.
01111111 = 0xBD07_FFFF

bit 11-4 **Reserved**: Write '1'

bit 3 **ICESEL**: In-Circuit Emulator/Debugger Communication Channel Select bit

1 = PGEC2/PGED2 pair is used
0 = PGEC1/PGED1 pair is used

bit 2 **Reserved**: Write '1'

bit 1-0 **DEBUG<1:0>**: Background Debugger Enable bits (forced to '11' if code-protect is enabled)

11 = Debugger disabled
10 = Debugger enabled
01 = Reserved (same as '11' setting)
00 = Reserved (same as '11' setting)

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TABLE 29-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD}) (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp			
Parameter No.	Typical ⁽²⁾	Max.	Units	Conditions		
Module Differential Current (Continued)						
DC43	—	1100	μA	-40°C	2.5V	ADC: ΔIADC (Notes 3, 4, 6)
DC43a	—	1100	μA	+25°C		
DC43b	—	1000	μA	+85°C		
DC43h	—	1200	μA	+105°C		
DC43c	880	—	μA	—	—	ADC: ΔIADC (Notes 3, 4)
DC43e	—	1100	μA	-40°C	3.6V	ADC: ΔIADC (Notes 3, 4)
DC43f	—	1100	μA	+25°C		
DC43g	—	1000	μA	+85°C		
DC43i	—	1200	μA	+105°C		

- Note 1:** Base I_{PD} is measured with all digital peripheral modules disabled. All I/Os are configured as inputs and pulled low. WDT and FSCM are disabled.
- 2:** Data in the “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.
- 3:** The Δ current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current.
- 4:** Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.
- 5:** Data is characterized at +70°C and not tested. Parameter is for design guidance only.
- 6:** This parameter is characterized, but not tested in manufacturing.

TABLE 29-8: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	Symbol	Characteristics	Min.	Typical ⁽¹⁾	Max.	Units	Conditions
DI10	VI _L	Input Low Voltage I/O pins: with TTL Buffer	V _{SS}	—	0.15 V _{DD}	V	(Note 4)
		with Schmitt Trigger Buffer	V _{SS}	—	0.2 V _{DD}	V	(Note 4)
DI15		<u>MCLR</u>	V _{SS}	—	0.2 V _{DD}	V	(Note 4)
DI16		OSC1 (XT mode)	V _{SS}	—	0.2 V _{DD}	V	(Note 4)
DI17		OSC1 (HS mode)	V _{SS}	—	0.2 V _{DD}	V	(Note 4)
DI18		SDAx, SCLx	V _{SS}	—	0.3 V _{DD}	V	SMBus disabled (Note 4)
DI19		SDAx, SCLx	V _{SS}	—	0.8	V	SMBus enabled (Note 4)
DI20	VI _H	Input High Voltage I/O pins: with Analog Functions	0.8 V _{DD}	—	V _{DD}	V	(Note 4)
		Digital Only	0.8 V _{DD}	—		V	(Note 4)
		with TTL Buffer	0.25V _{DD} + 0.8V	—	5.5	V	(Note 4)
		with Schmitt Trigger Buffer	0.8 V _{DD}	—	5.5	V	(Note 4)
DI25		<u>MCLR</u>	0.8 V _{DD}	—	V _{DD}	V	(Note 4)
DI26		OSC1 (XT mode)	0.7 V _{DD}	—	V _{DD}	V	(Note 4)
DI27		OSC1 (HS mode)	0.7 V _{DD}	—	V _{DD}	V	(Note 4)
DI28		SDAx, SCLx	0.7 V _{DD}	—	5.5	V	SMBus disabled (Note 4)
DI29		SDAx, SCLx	2.1	—	5.5	V	SMBus enabled, 2.3V ≤V _{PIN} ≤5.5 (Note 4)
DI30	IC _{NPU}	CNxx Pull up Current	50	250	400	μA	V _{DD} = 3.3V, V _{PIN} = V _{SS}
DI50	I _{IL}	Input Leakage Current I/O Ports	—	—	±1	μA	(Note 3) V _{SS} ≤V _{PIN} ≤V _{DD} , Pin at high-impedance
DI51		Analog Input Pins	—	—	±1	μA	V _{SS} ≤V _{PIN} ≤V _{DD} , Pin at high-impedance
DI55		<u>MCLR</u>	—	—	±1	μA	V _{SS} ≤V _{PIN} ≤V _{DD}
DI56		OSC1	—	—	±1	μA	V _{SS} ≤V _{PIN} ≤V _{DD} , XT and HS modes

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: This parameter is characterized, but not tested in manufacturing.

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TABLE 29-17: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	Symbol	Characteristics	Min.	Typical ⁽¹⁾	Max.	Units	Conditions
OS10	Fosc	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC 4	— —	50 ⁽³⁾ 50 ⁽⁵⁾	MHz MHz	EC (Note 5) ECPLL (Note 4)
OS11		Oscillator Crystal Frequency	3	—	10	MHz	XT (Note 5)
OS12			4	—	10	MHz	XTPLL (Notes 4, 5)
OS13			10	—	25	MHz	HS (Note 5)
OS14			10	—	25	MHz	HSPLL (Notes 4, 5)
OS15			32	32.768	100	kHz	Sosc (Note 5)
OS20	Tosc	Tosc = 1/Fosc = Tcy ⁽²⁾	—	—	—	—	See parameter OS10 for Fosc value
OS30	TosL, TosH	External Clock In (OSC1) High or Low Time	0.45 x Tosc	—	—	ns	EC (Note 5)
OS31	TosR, TosF	External Clock In (OSC1) Rise or Fall Time	—	—	0.05 x Tosc	ns	EC (Note 5)
OS40	TOST	Oscillator Start-up Timer Period (Only applies to HS, HSPLL, XT, XTPLL and Sosc Clock Oscillator modes)	—	1024	—	Tosc	(Note 5)
OS41	TFSCM	Primary Clock Fail Safe Time-out Period	—	2	—	ms	(Note 5)
OS42	GM	External Oscillator Transconductance	—	12	—	mA/V	VDD = 3.3V TA = +25°C (Note 5)

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are characterized but are not tested.

- 2:** Instruction cycle period (Tcy) equals the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKI pin.
- 3:** 40 MHz maximum for PIC32MX320F032H and PIC32MX420F032H devices.
- 4:** PLL input requirements: 4 MHz ≤F_{PLLIN} ≤5 MHz (use PLL prescaler to reduce Fosc). This parameter is characterized, but tested at 10 MHz only at manufacturing.
- 5:** This parameter is characterized, but not tested in manufacturing.

TABLE 29-18: PLL CLOCK TIMING SPECIFICATIONS (V_{DD} = 2.3V TO 3.6V)

AC CHARACTERISTICS		Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤T _A ≤+85°C for Industrial -40°C ≤T _A ≤+105°C for V-Temp					
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Typical	Max.	Units	Conditions
OS50	FPLLI	PLL Voltage Controlled Oscillator (VCO) Input Frequency Range	4	—	5	MHz	ECPLL, HSPLL, XTPLL, FRCPLL modes
OS51	FSYS	On-Chip VCO System Frequency	60	—	120	MHz	—
OS52	TLOCK	PLL Start-up Time (Lock Time)	—	—	2	ms	—
OS53	DCLK	CLKO Stability ⁽²⁾ (Period Jitter or Cumulative)	-0.25	—	+0.25	%	Measured over 100 ms period

Note 1: These parameters are characterized, but not tested in manufacturing.

2: This jitter specification is based on clock-cycle by clock-cycle measurements. To get the effective jitter for individual time-bases on communication clocks, use the following formula:

$$EffectiveJitter = \frac{D_{CLK}}{\sqrt{\frac{SYSCLK}{CommunicationClock}}}$$

For example, if SYSCLK = 80 MHz and SPI bit rate = 20 MHz, the effective jitter is as follows:

$$EffectiveJitter = \frac{D_{CLK}}{\sqrt{\frac{80}{20}}} = \frac{D_{CLK}}{2}$$

TABLE 29-19: INTERNAL FRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤T _A ≤+85°C for Industrial -40°C ≤T _A ≤+105°C for V-Temp				
Param. No.	Characteristics	Min.	Typical	Max.	Units	Conditions
Internal FRC Accuracy @ 8.00 MHz⁽¹⁾						
F20	FRC	-2	—	+2	%	—

Note 1: Frequency calibrated at 25°C and 3.3V. TUN bits can be used to compensate for temperature drift.

TABLE 29-20: INTERNAL RC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤T _A ≤+85°C for Industrial -40°C ≤T _A ≤+105°C for V-Temp				
Param. No.	Characteristics	Min.	Typical	Max.	Units	Conditions
LPRC @ 31.25 kHz⁽¹⁾						
F21	LPRC	-15	—	+15	%	—

Note 1: Change of LPRC frequency as V_{DD} changes.

PIC32MX3XX/4XX

FIGURE 29-11: SPIx MODULE MASTER MODE (CKE = 1) TIMING CHARACTERISTICS

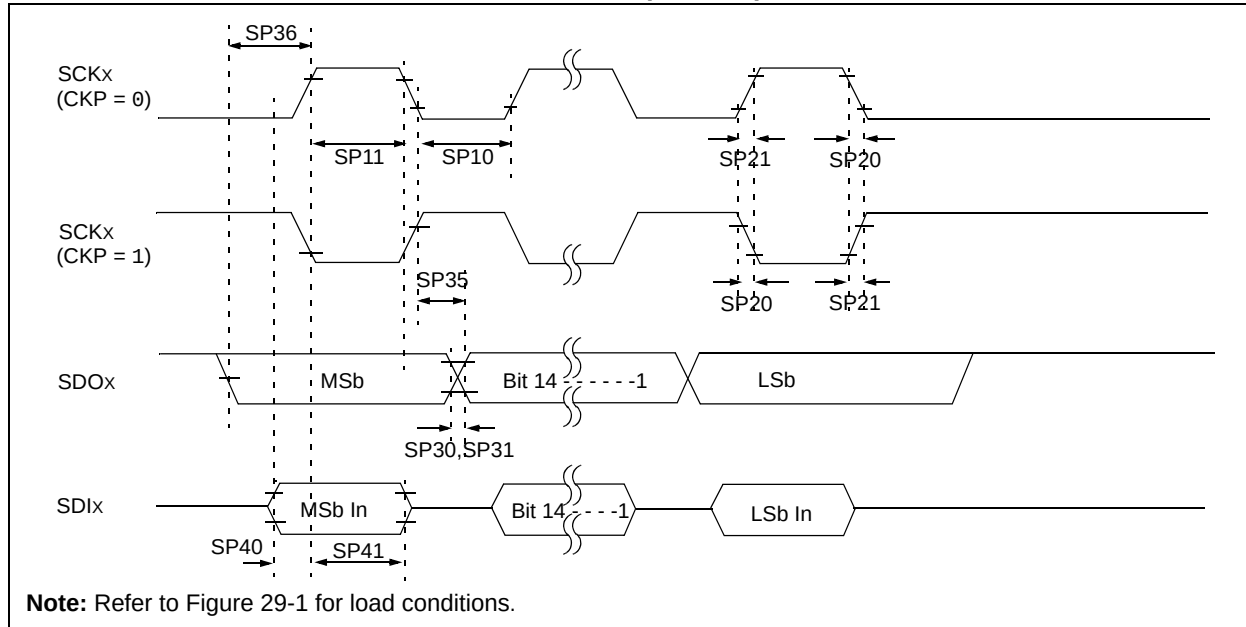


TABLE 29-29: SPIx MODULE MASTER MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp				
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Typical ⁽²⁾	Max.	Units	Conditions
SP10	TsCL	SCKx Output Low Time ⁽³⁾	TsCK/2	—	—	ns	—
SP11	TsCH	SCKx Output High Time ⁽³⁾	TsCK/2	—	—	ns	—
SP20	TscF	SCKx Output Fall Time ⁽⁴⁾	—	—	—	ns	See parameter DO32
SP21	TscR	SCKx Output Rise Time ⁽⁴⁾	—	—	—	ns	See parameter DO31
SP30	TdOF	SDOx Data Output Fall Time ⁽⁴⁾	—	—	—	ns	See parameter DO32
SP31	TdOR	SDOx Data Output Rise Time ⁽⁴⁾	—	—	—	ns	See parameter DO31
SP35	TsCH2DoV, TsCL2DoV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	VDD > 2.7V
			—	—	20	ns	VDD < 2.7V
SP36	TdOV2sc, TdOV2sCL	SDOx Data Output Setup to First SCKx Edge	15	—	—	ns	—
SP40	TdIV2sCH, TdIV2sCL	Setup Time of SDIx Data Input to SCKx Edge	15	—	—	ns	VDD > 2.7V
			20	—	—	ns	VDD < 2.7V
SP41	TsCH2DiL, TsCL2DiL	Hold Time of SDIx Data Input to SCKx Edge	15	—	—	ns	VDD > 2.7V
			20	—	—	ns	VDD < 2.7V

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 40 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

TABLE 29-35: 10-BIT ADC CONVERSION RATE PARAMETERS⁽²⁾

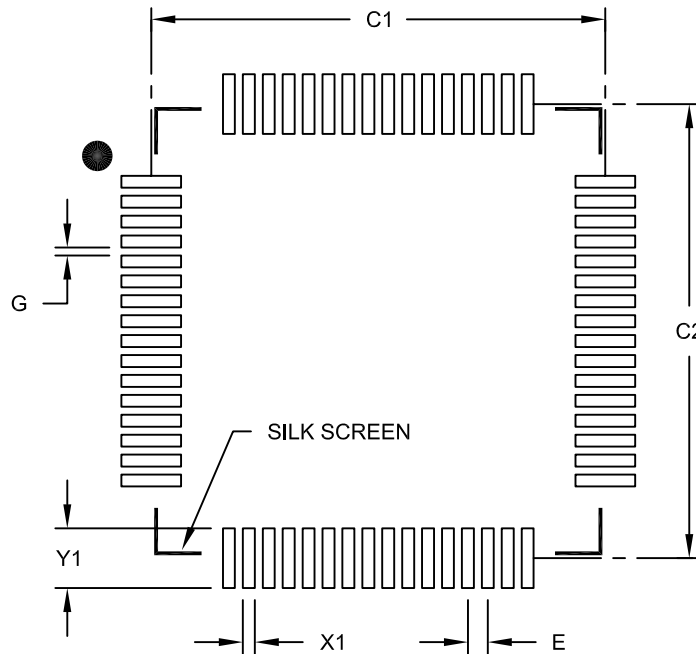
Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-Temp					
ADC Speed	TAD Minimum	Sampling Time Min	Rs Max	VDD	ADC Channels Configuration
1 MIPS to 400 ksps ⁽¹⁾	65 ns	132 ns	500Ω	3.0V to 3.6V	
Up to 400 ksps	200 ns	200 ns	5.0 kΩ	2.5V to 3.6V	
Up to 300 ksps	200 ns	200 ns	5.0 kΩ	2.5V to 3.6V	

Note 1: External VREF- and VREF+ pins must be used for correct operation.

2: These parameters are characterized, but not tested in manufacturing.

64-Lead Plastic Thin Quad Flatpack (PT) 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

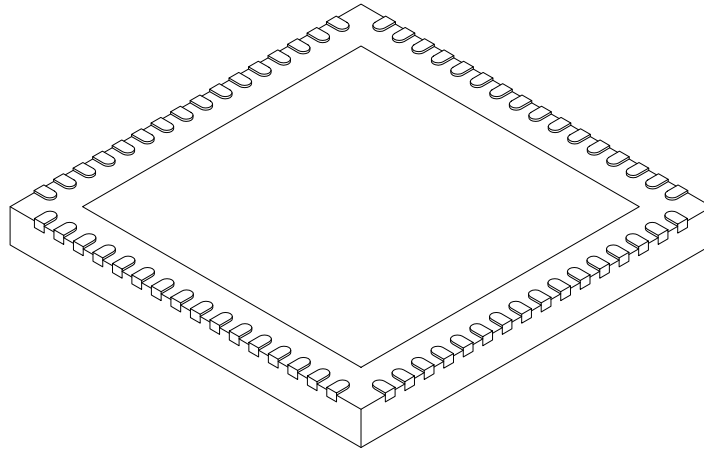
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2085B

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [QFN] With 7.15 x 7.15 Exposed Pad [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	64		
Pitch	e	0.50 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3	0.20 REF		
Overall Width	E	9.00 BSC		
Exposed Pad Width	E2	7.05	7.15	7.50
Overall Length	D	9.00 BSC		
Exposed Pad Length	D2	7.05	7.15	7.50
Contact Width	b	0.18	0.25	0.30
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-149C Sheet 2 of 2